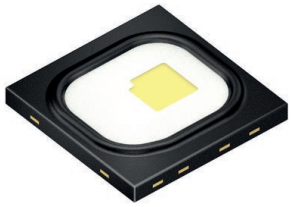
LCG H9RM



OSRAM OSTAR® Projection Cube

OSRAM OSTAR Projection Cube is a high flux LED for slim designs.

Applications

- Projection Home LED & Laser
- Projection Mobile (LED & Laser)

Features:

- Package: SMD epoxy package
- Chip technology: UX:3
- Typ. Radiation: 120° (Lambertian emitter)
- Color: Cx = 0.318, Cy = 0.642 acc. to CIE 1931 (● converted green)
- Corrosion Robustness Class: 3B
- ESD: 8 kV acc. to ANSI/ESDA/JEDEC JS-001 (HBM, Class 3B)

Ordering Information

Type	Luminous Flux [1] I_F = 350 mA Φ_V	Ordering Code
LCG H9RM-LXMX-2	112 ... 210 lm	Q65112A6831

Maximum Ratings

Parameter	Symbol		Values
Operating Temperature	T_{op}	min. max.	-40 °C 100 °C
Storage Temperature	T_{stg}	min. max.	-40 °C 100 °C
Junction Temperature	T_j	max.	150 °C
Forward Current T_S = 25 °C	I_F	min. max.	100 mA 500 mA
Forward Current pulsed D = 0.5 ; f = 120 Hz; T_S = 25 °C	$I_{F\ pulse}$		1000 mA
ESD withstand voltage acc. to ANSI/ESDA/JEDEC JS-001 (HBM, Class 3B)	V_{ESD}		8 kV
Reverse current [2)]	I_R	max.	200 mA

Characteristics

I_F = 350 mA; T_S = 25 °C

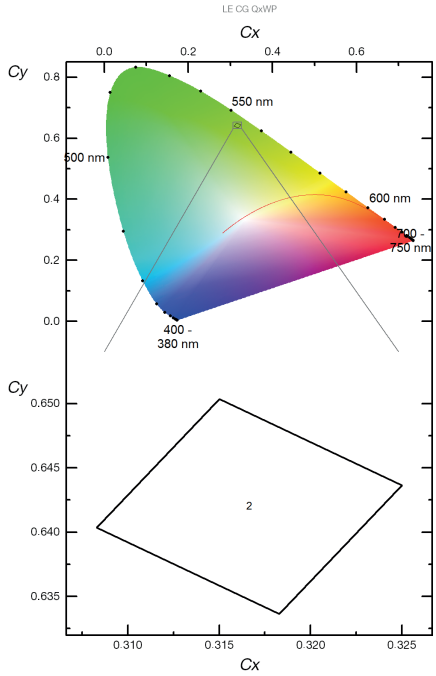
Parameter	Symbol		Values
Chromaticity Coordinate [3] acc. to CIE 1931 within λ = 500 ... 600 nm	Cx Cy	typ. typ.	0.318 0.642
Viewing angle at 50% I_V	2φ	typ.	120 °
Radiating surface	A_{color}	typ.	0.72 x 0.72 mm²
Partial Flux acc. CIE 127:2007 [4] I_F = 350 mA	$\Phi_{E/V,\ 120°}$	typ.	0.77
Forward Voltage [5] I_F = 350 mA	V_F	min. typ. max.	2.70 V 2.97 V 3.50 V
Reverse voltage (ESD device)	$V_{R\ ESD}$	min.	45 V
Reverse voltage [2] I_R = 20 mA	V_R	max.	1.2 V
Real thermal resistance junction/solderpoint [6]	$R_{thJS\ real}$	typ. max.	8.3 K / W 10.0 K / W
Electrical thermal resistance junction/solderpoint [6] with efficiency η_e = 29 %	$R_{thJS\ elec.}$	typ. max.	5.9 K / W 7.1 K / W

Brightness Groups

Group	Luminous Flux [1] I_F = 350 mA min. Φ_V	Luminous Flux [1] I_F = 350 mA max. Φ_V	Luminous Intensity [4] I_F = 350 mA typ. I_v
LX	112 lm	130 lm	41 cd
LY	130 lm	150 lm	47 cd
LZ	150 lm	180 lm	55 cd
MX	180 lm	210 lm	66 cd

Chromaticity Coordinate Groups

within λ = 500 ... 600 nm



Chromaticity Coordinate Groups [3)]

Group	Cx	Cy
2	0.3083	0.6404
	0.3150	0.6504
	0.3250	0.6437
	0.3183	0.6337

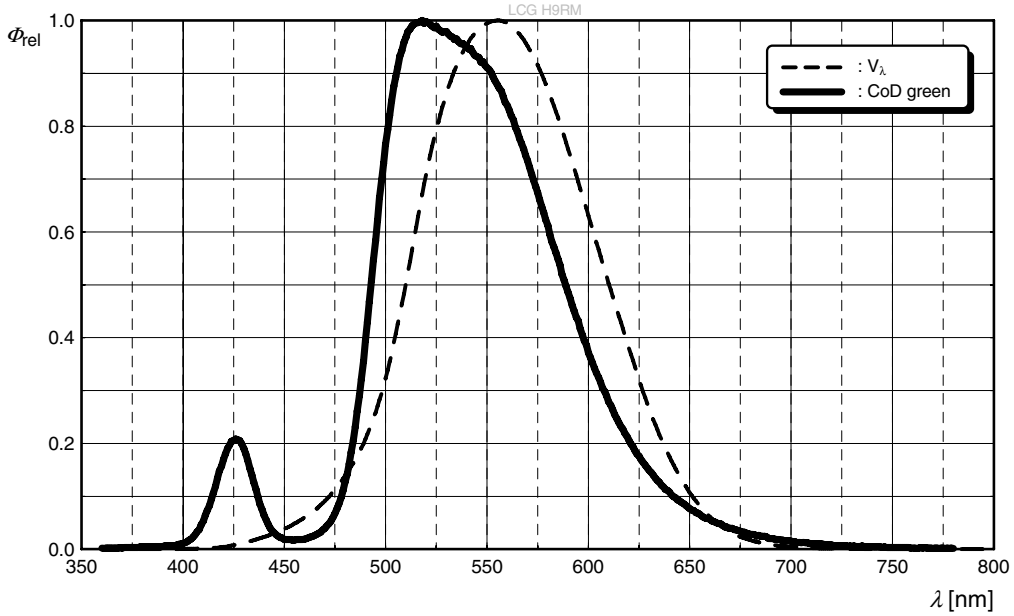
Group Name on Label

Example: LX-2

Brightness	Color Chromaticity
LX	2

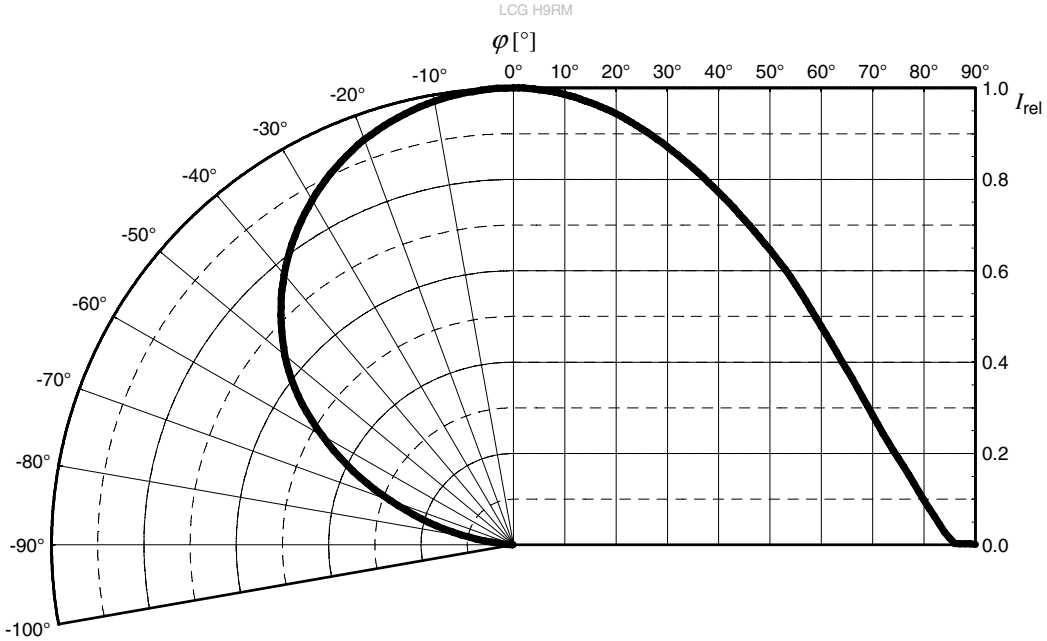
Relative Spectral Emission [4)]

$\Phi_{rel} = f(\lambda)$; I_F = 350 mA; T_J = 25 °C



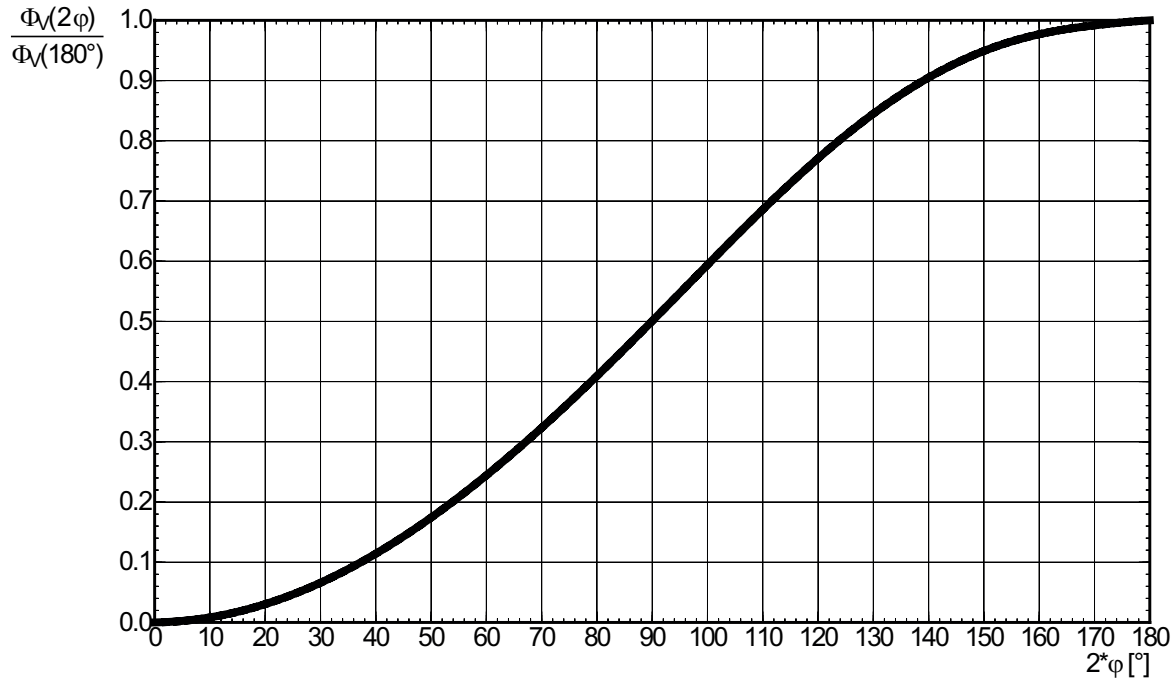
Radiation Characteristics [4)]

$I_{rel} = f(\phi)$; T_J = 25 °C



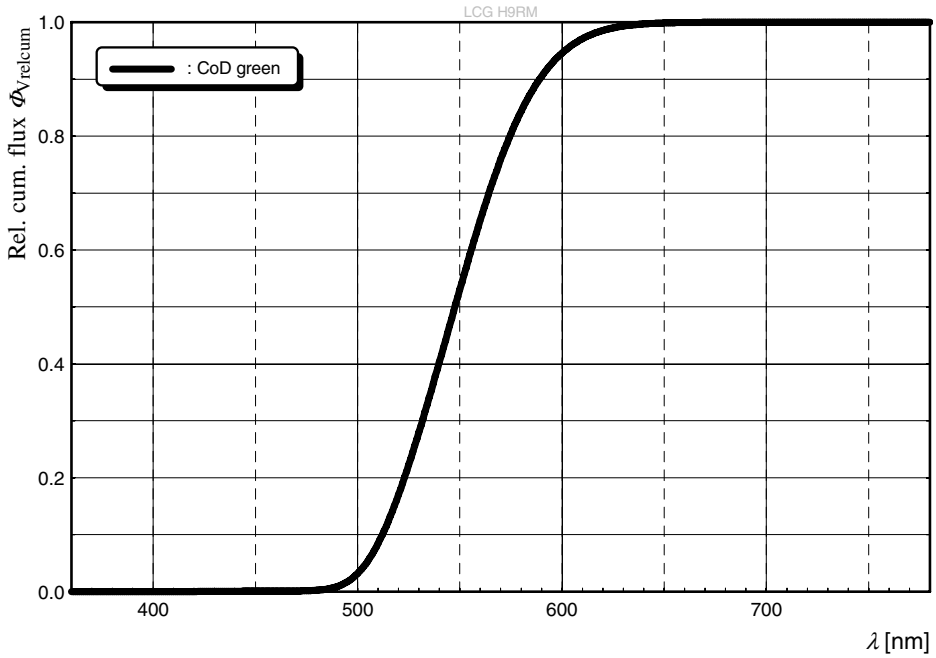
Relative Partial Flux [4)]

$\Phi_v(2\varphi)/\Phi_v(180°) = f(\varphi)$; T_J = 25 °C



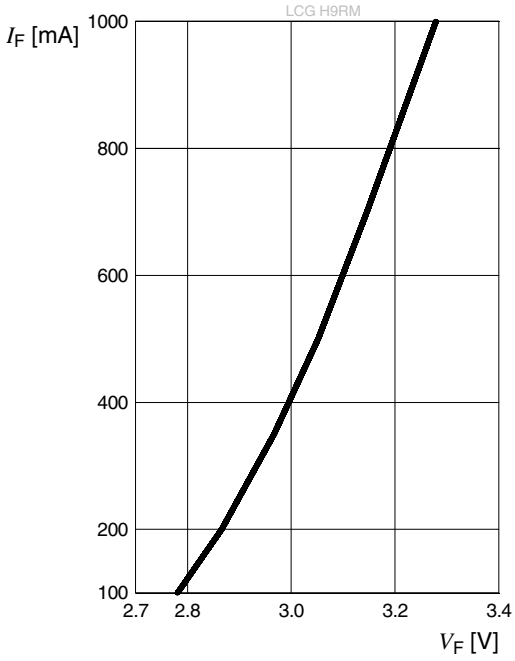
Relative cumulated Luminous Flux [4)]

$\Phi_{Vrel - cum} = f(\lambda)$; I_F = 350 mA; T_J = 25 °C



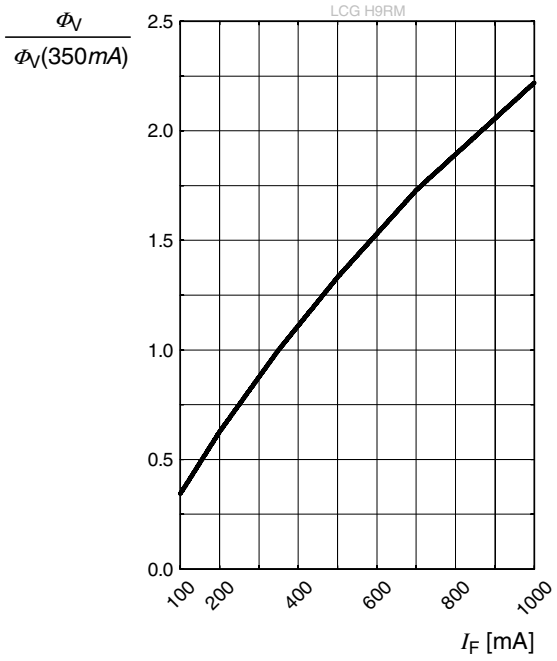
Forward current 4), 7)

$I_F = f(V_F)$; T_J = 25 °C



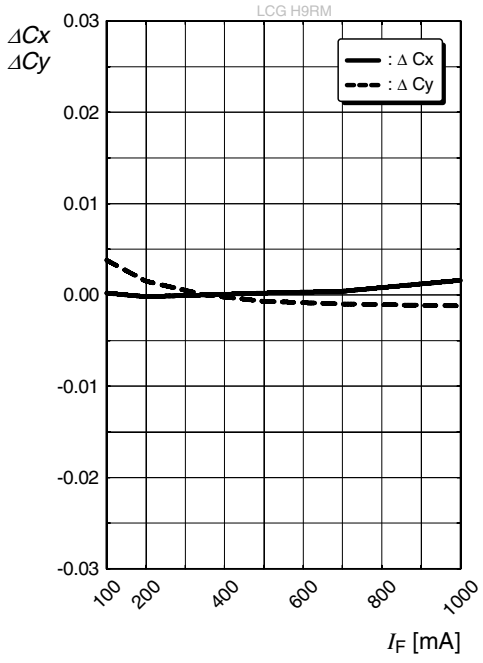
Relative Luminous Flux 4), 7)

$\Phi_v/\Phi_v(350\ mA) = f(I_F)$; T_J = 25 °C



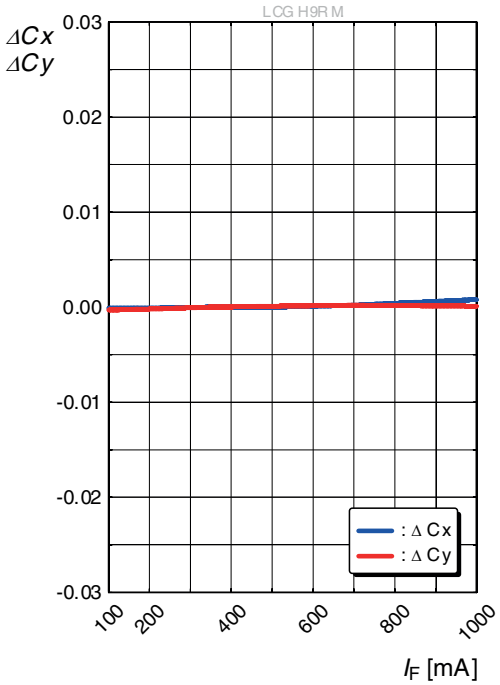
Chromaticity Coordinate Shift 4)

ΔCx, ΔCy = $f(I_F)$; T_J = 25 °C; full spectral range



Chromaticity Coordinate Shift 4)

ΔCx, ΔCy = $f(I_F)$; T_J = 25 °C; within λ = 500 ... 600 nm



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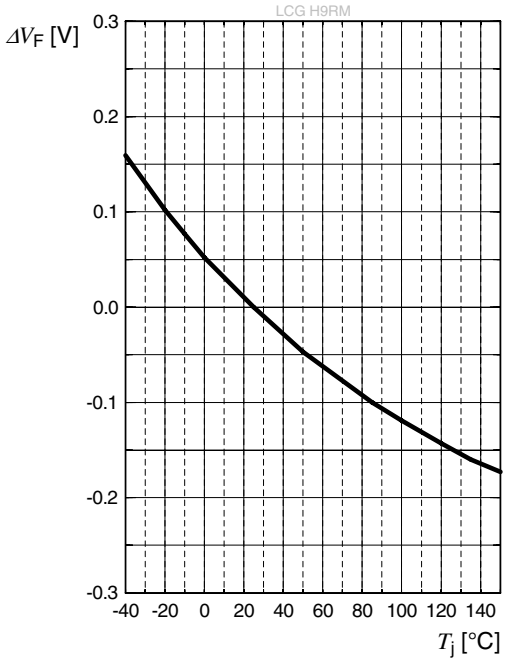
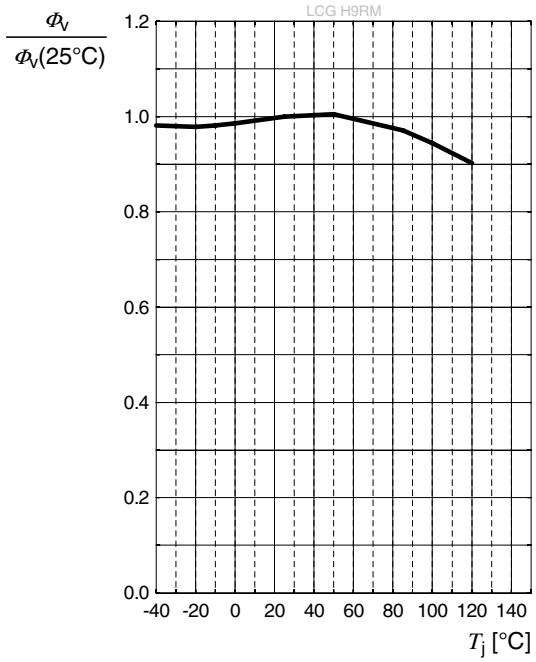
Forward Voltage [4]

$\Delta V_F = V_F - V_F(25\ °C) = f(T_j);\ I_F = 350\ mA$



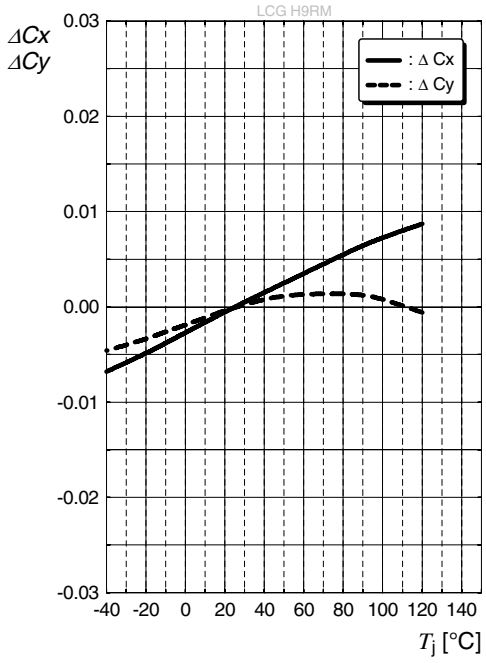
Relative Luminous Flux [4]

$\Phi_v/\Phi_v(25\ °C) = f(T_j);\ I_F = 350\ mA$



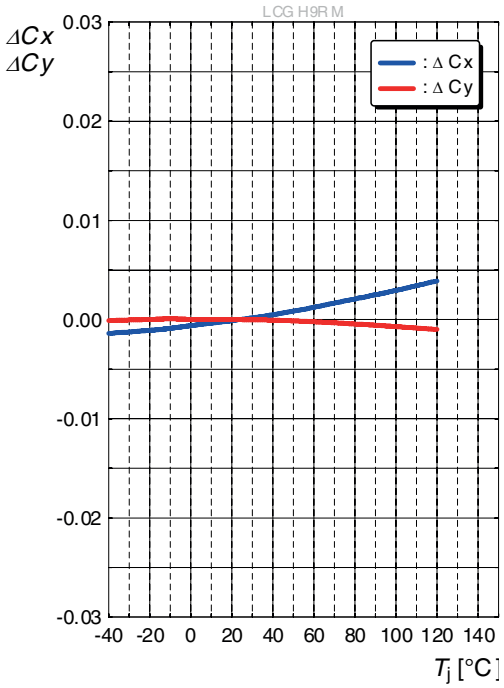
Chromaticity Coordinate Shift [4]

$\Delta Cx, \Delta Cy = f(T_j);\ I_F = 350\ mA$; full spectral range



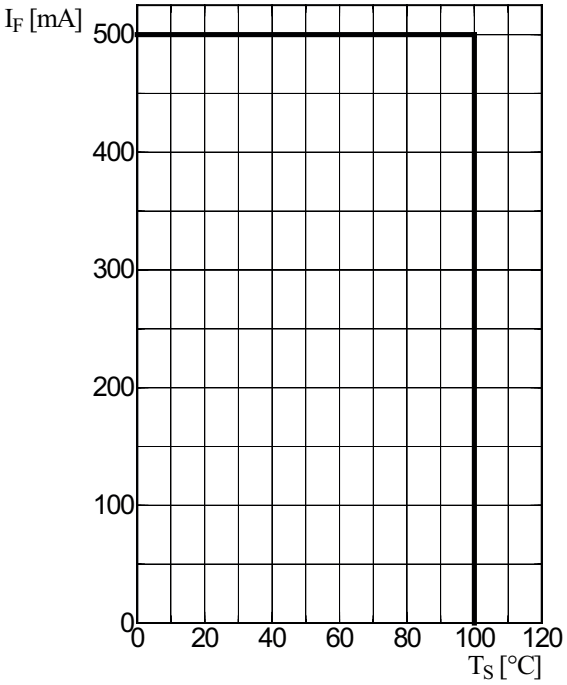
Chromaticity Coordinate Shift [4]

$\Delta Cx, \Delta Cy = f(T_j);\ I_F = 350\ mA$; within λ = 500 ... 600 nm

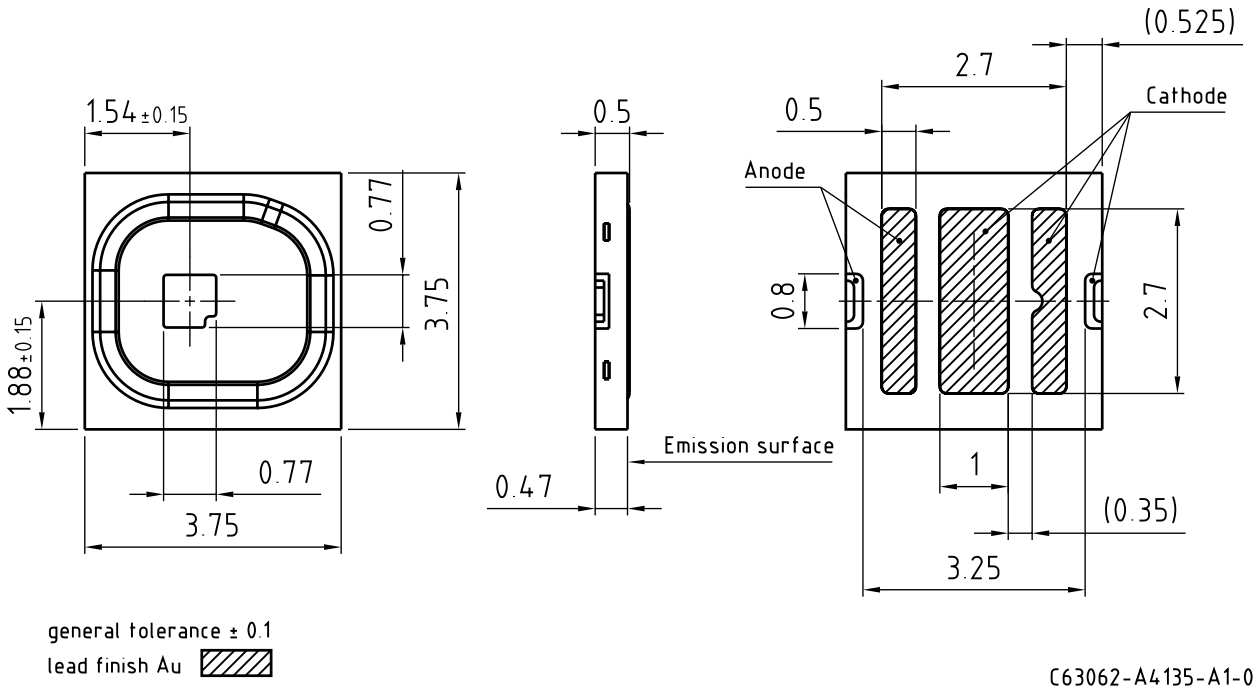


Max. Permissible Forward Current

$I_F = f(T)$



Dimensional Drawing [8)]



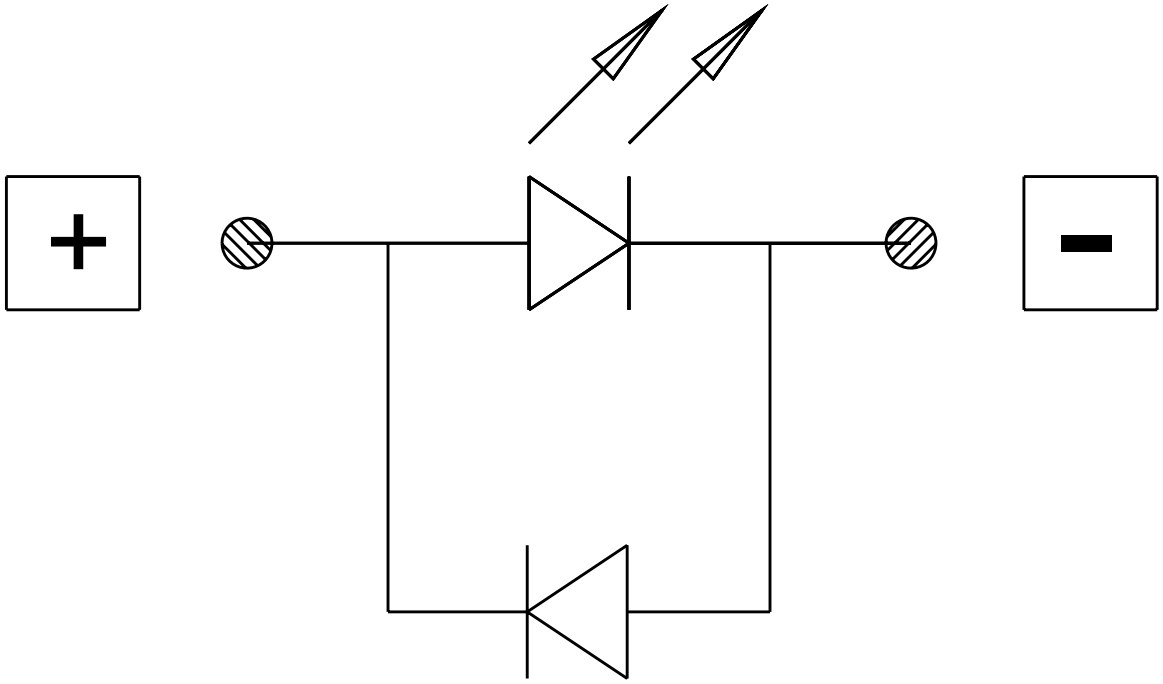
Further Information:

Approximate Weight: 22.0 mg

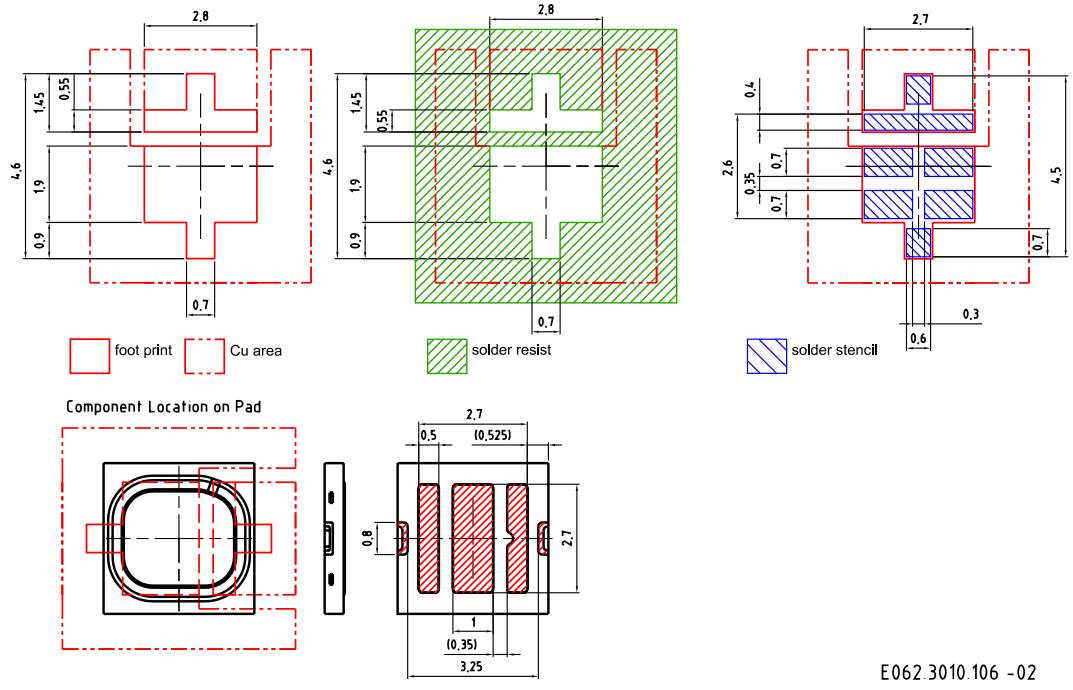
Corrosion test: Class: 3B
Test condition: 40°C / 90 % RH / 15 ppm H_2S / 14 days (stricter than IEC 60068-2-43)

ESD advice: The device is protected by ESD device which is connected in parallel to the Chip.

Electrical Internal Circuit



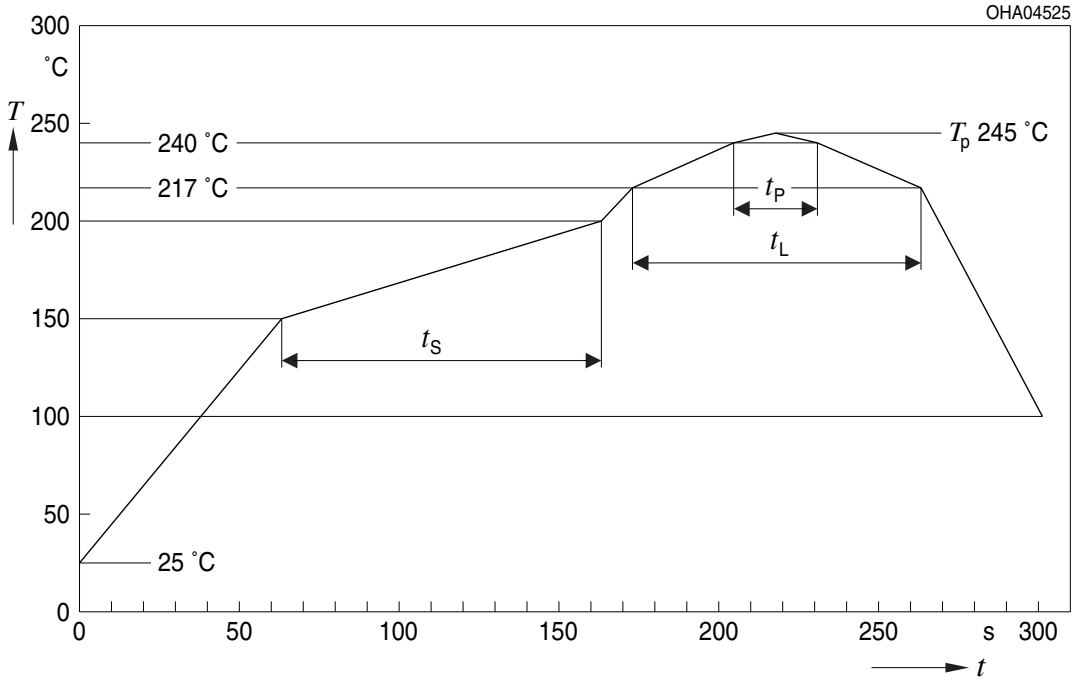
Recommended Solder Pad [8)]



For superior solder joint connectivity results we recommend soldering under standard nitrogen atmosphere. In case the PCB layout of the application is intended to be used with other OSLON derivates or in future developed OSLON derivates, the heat sink must not be electrically connected to anode or cathode solder pad because of possible chip inverted polarity. Package not suitable for ultra sonic cleaning.

Reflow Soldering Profile

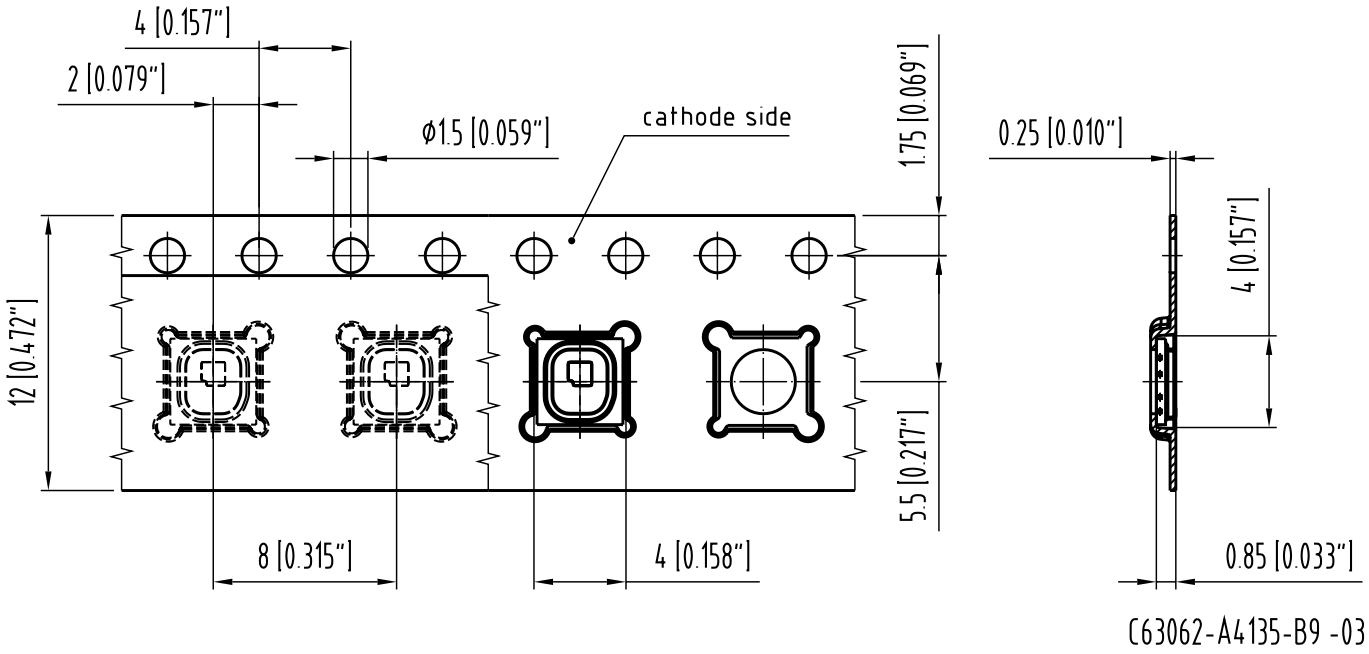
Product complies to MSL Level 2 acc. to JEDEC J-STD-020E



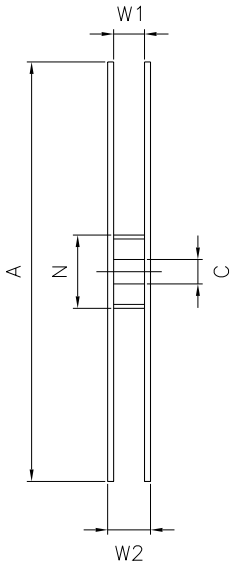
Profile Feature	Symbol	Pb-Free (SnAgCu) Assembly			Unit
		Minimum	Recommendation	Maximum	
Ramp-up rate to preheat*) 25 °C to 150 °C			2	3	K/s
Time t_S T_{Smin} to T_{Smax}	t_S	60	100	120	s
Ramp-up rate to peak*) T_{Smax} to T_P			2	3	K/s
Liquidus temperature	T_L		217		°C
Time above liquidus temperature	t_L		80	100	s
Peak temperature	T_P		245	260	°C
Time within 5 °C of the specified peak temperature T_P - 5 K	t_P	10	20	30	s
Ramp-down rate* T_P to 100 °C			3	6	K/s
Time 25 °C to T_P				480	s

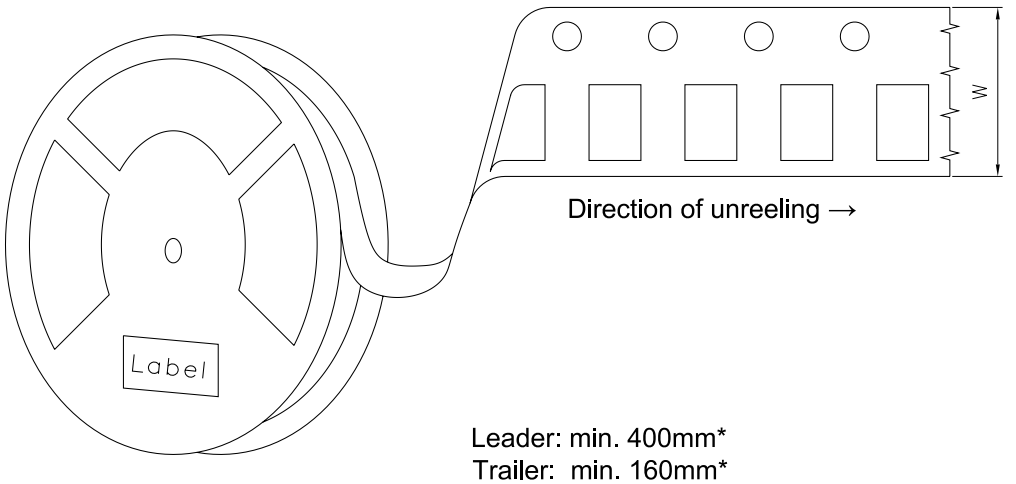
All temperatures refer to the center of the package, measured on the top of the component
* slope calculation DT/Dt: Dt max. 5 s; fulfillment for the whole T-range

Taping [8)]


4 [0.157"]
2 [0.079"]
ø1.5 [0.059"]
cathode side
1.75 [0.069"]
0.25 [0.010"]
12 [0.472"]
4 [0.157"]
5.5 [0.217"]
8 [0.315"]
4 [0.158"]
0.85 [0.033"]
C63062-A4135-B9 -03

Tape and Reel [9)]



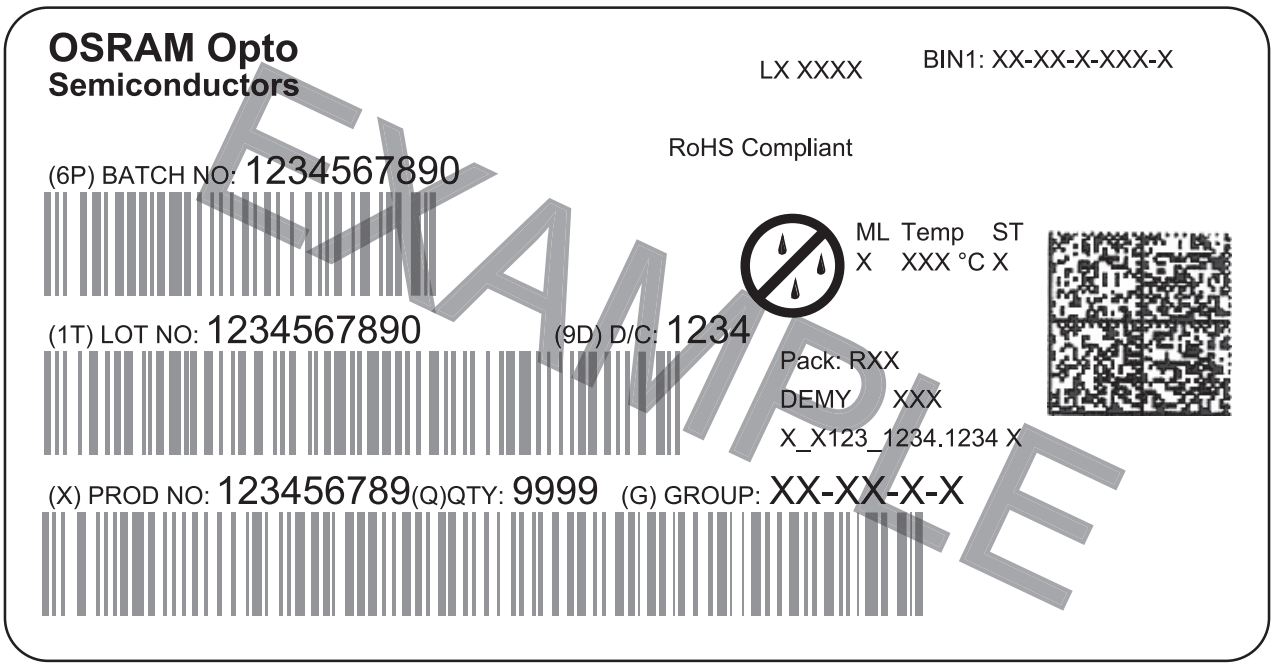


Leader: min. 400mm*
Trailer: min. 160mm*
*)Dimensions acc. to IEC 60286-3; EIA 481-E

Reel Dimensions

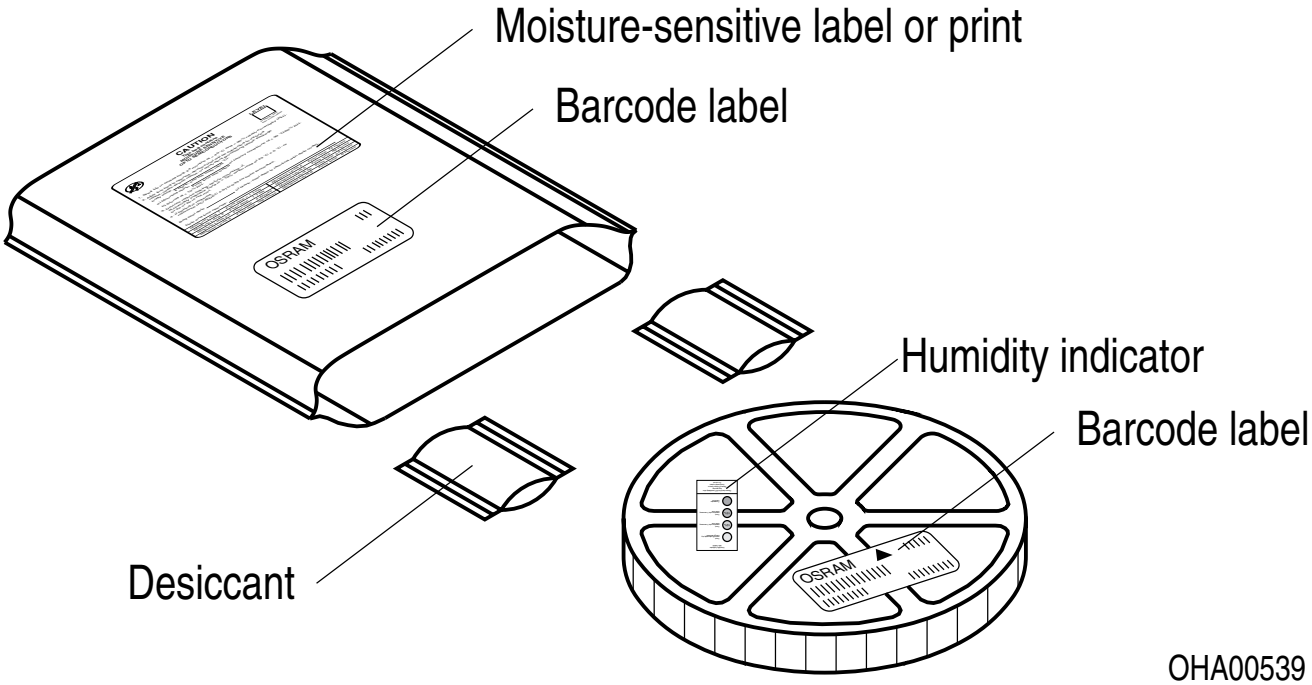
A	W	N_{min}	W_1	$W_{2\,max}$	Pieces per PU
180 mm	12 + 0.3 / - 0.1 mm	60 mm	12.4 + 2 mm	18.4 mm	2000

Barcode-Product-Label (BPL)



OHA04563

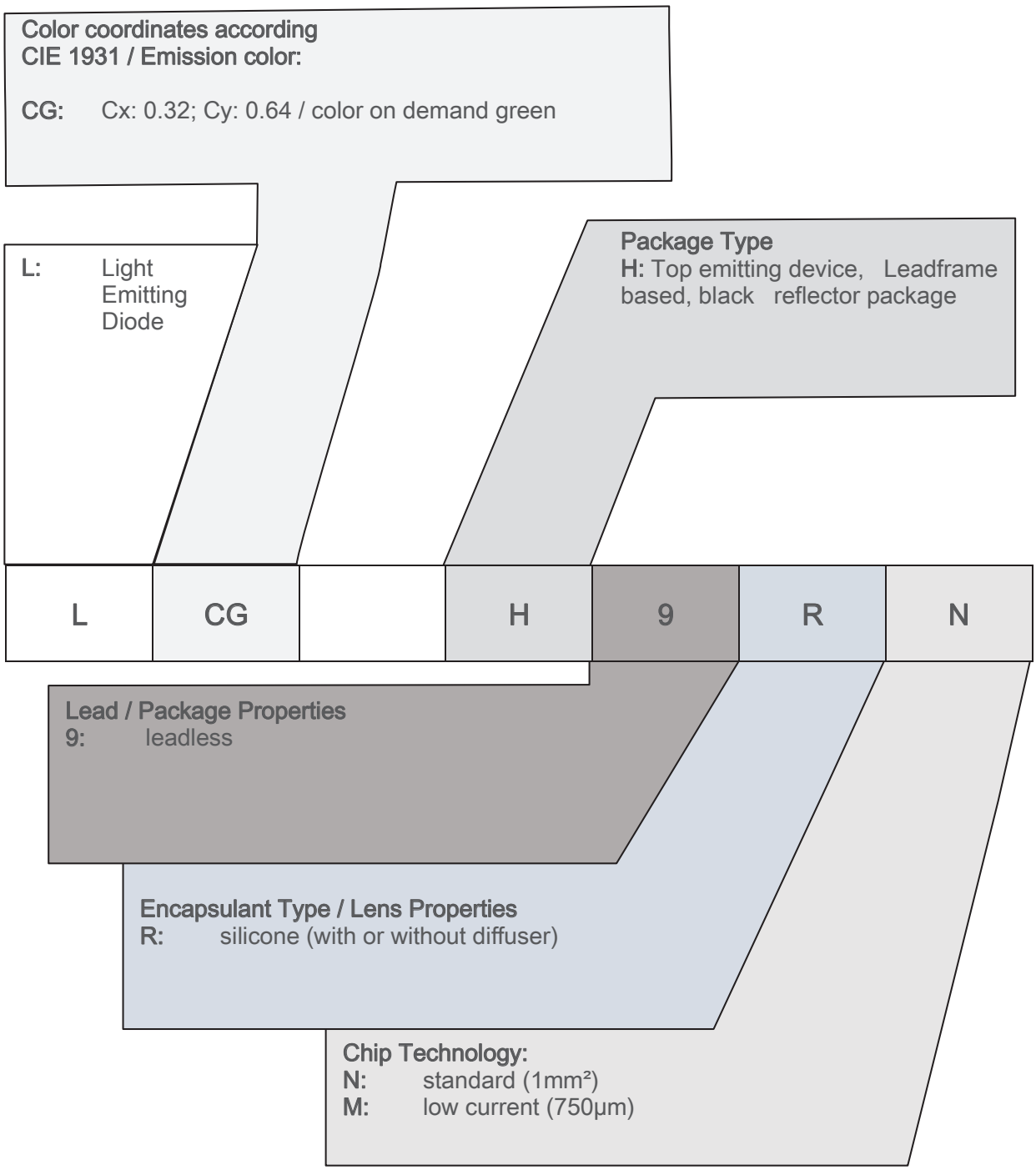
Dry Packing Process and Materials [8)]



OHA00539

Moisture-sensitive product is packed in a dry bag containing desiccant and a humidity card according JEDEC-STD-033.

Type Designation System



Notes

The evaluation of eye safety occurs according to the standard IEC 62471:2006 (photo biological safety of lamps and lamp systems). Within the risk grouping system of this IEC standard, the device specified in this data sheet falls into the class **low risk (exposure time 100 s)**. Under real circumstances (for exposure time, conditions of the eye pupils, observation distance), it is assumed that no endangerment to the eye exists from these devices. As a matter of principle, however, it should be mentioned that intense light sources have a high secondary exposure potential due to their blinding effect. When looking at bright light sources (e.g. headlights), temporary reduction in visual acuity and afterimages can occur, leading to irritation, annoyance, visual impairment, and even accidents, depending on the situation.

Subcomponents of this device contain, in addition to other substances, metal filled materials including silver. Metal filled materials can be affected by environments that contain traces of aggressive substances. Therefore, we recommend that customers minimize device exposure to aggressive substances during storage, production, and use. Devices that showed visible discoloration when tested using the described tests above did show no performance deviations within failure limits during the stated test duration. Respective failure limits are described in the IEC60810.

For further application related information please visit www.osram-os.com/appnotes

Disclaimer

Attention please!
The information describes the type of component and shall not be considered as assured characteristics.
Terms of delivery and rights to change design reserved. Due to technical requirements components may contain dangerous substances.
For information on the types in question please contact our Sales Organization.
If printed or downloaded, please find the latest version on the OSRAM OS website.

Packing
Please use the recycling operators known to you. We can also help you – get in touch with your nearest sales office. By agreement we will take packing material back, if it is sorted. You must bear the costs of transport. For packing material that is returned to us unsorted or which we are not obliged to accept, we shall have to invoice you for any costs incurred.

Product and functional safety devices/applications or medical devices/applications
OSRAM OS components are not developed, constructed or tested for the application as safety relevant component or for the application in medical devices.
OSRAM OS products are not qualified at module and system level for such application.

In case buyer – or customer supplied by buyer – considers using OSRAM OS components in product safety devices/applications or medical devices/applications, buyer and/or customer has to inform the local sales partner of OSRAM OS immediately and OSRAM OS and buyer and /or customer will analyze and coordinate the customer-specific request between OSRAM OS and buyer and/or customer.

Glossary

1) **Brightness:** Brightness values are measured during a current pulse of typically 25 ms, with an internal reproducibility of ±8 % and an expanded uncertainty of ±11 % (acc. to GUM with a coverage factor of k = 3).

2) **Reverse Operation:** This product is intended to be operated applying a forward current within the specified range. Applying any continuous reverse bias or forward bias below the voltage range of light emission shall be avoided because it may cause migration which can change the electro-optical characteristics or damage the LED.

3) **Chromaticity coordinate groups:** Chromaticity coordinates are measured during a current pulse of typically 25 ms, with an internal reproducibility of ±0.005 and an expanded uncertainty of ±0.01 (acc. to GUM with a coverage factor of k = 3).

4) **Typical Values:** Due to the special conditions of the manufacturing processes of semiconductor devices, the typical data or calculated correlations of technical parameters can only reflect statistical figures. These do not necessarily correspond to the actual parameters of each single product, which could differ from the typical data and calculated correlations or the typical characteristic line. If requested, e.g. because of technical improvements, these typ. data will be changed without any further notice.

5) **Forward Voltage:** The forward voltage is measured during a current pulse of typically 8 ms, with an internal reproducibility of ±0.05 V and an expanded uncertainty of ±0.1 V (acc. to GUM with a coverage factor of k = 3).

6) **Thermal Resistance:** Rth max is based on statistic values (6σ).

7) **Characteristic curve:** In the range where the line of the graph is broken, you must expect higher differences between single devices within one packing unit.

8) **Tolerance of Measure:** Unless otherwise noted in drawing, tolerances are specified with ±0.1 and dimensions are specified in mm.

9) **Tape and Reel:** All dimensions and tolerances are specified acc. IEC 60286-3 and specified in mm.

Revision History

Version	Date	Change
1.3	2018-12-13	Characteristics Chromaticity Coordinate Groups Dimensional Drawing
1.4	2019-01-08	Recommended Solder Pad
1.5	2020-06-03	Schematic Transportation Box Dimensions of Transportation Box

Published by OSRAM Opto Semiconductors GmbH
Leibnizstraße 4, D-93055 Regensburg

EU RoHS and China RoHS compliant product

此产品符合欧盟 RoHS 指令的要求；
按照中国的相关法规和标准，不含有毒有害物质或元素。